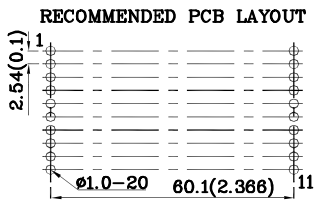
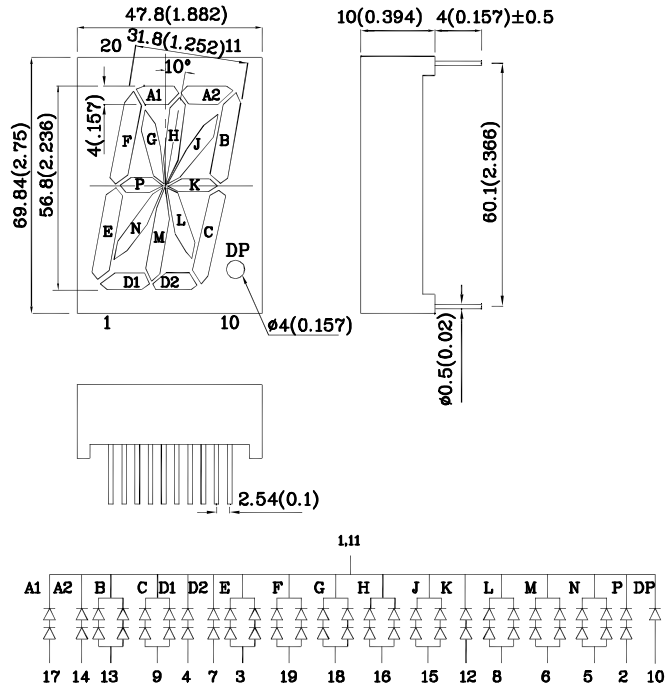


**Features**

- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant



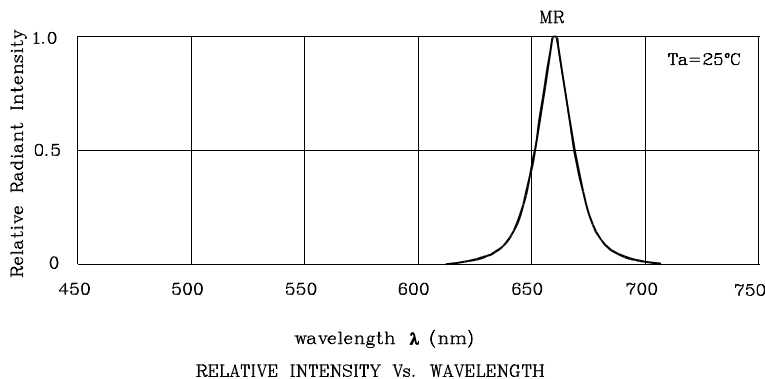
**Package Schematics**



**Notes:**

1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. Specifications are subject to change without notice.

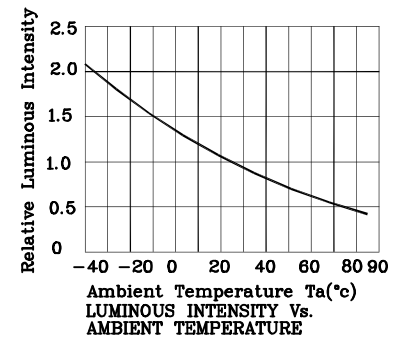
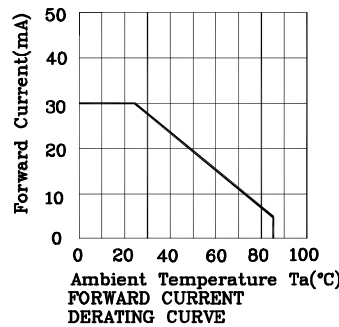
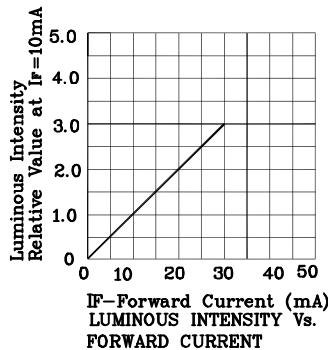
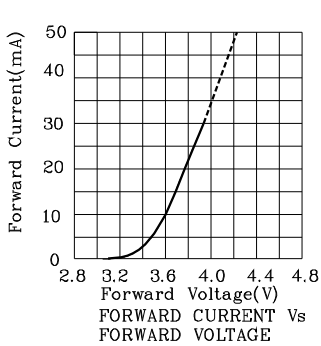
Part Number	Emitting Color	Emitting Material	Luminous Intensity ( $I_F=10\text{mA}$ ) ucd		Wavelength nm $\lambda_P$	Description
			min.	typ.		
XAMR60C	Red	GaAlAs	21000	43990	660	Common Cathode, Rt. Hand Decimal.



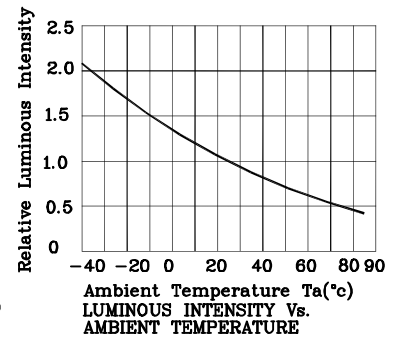
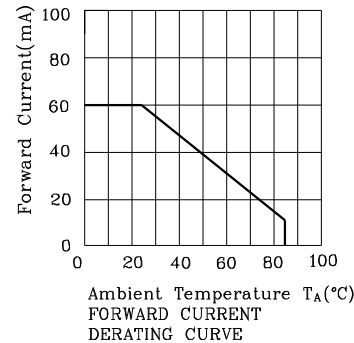
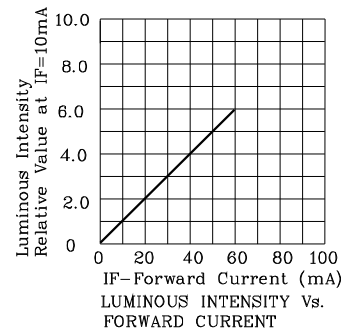
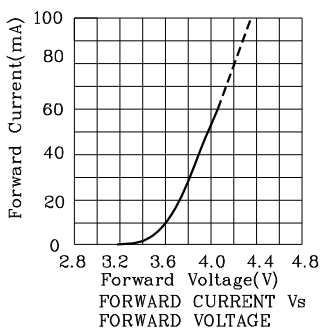
Absolute maximum ratings (TA=25°C)			UR (GaAsP/GaP)	Unit
Reverse Voltage	A1,A2,D1, D2,P,K	VR	5	V
	B,C,E,F,G, H,J,L,M,N		5	
	DP		5	
Forward Current	A1,A2,D1, D2,P,K	IF	30	mA
	B,C,E,F,G, H,J,L,M,N		60	
	DP		30	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	A1,A2,D1, D2,P,K	iFS	155	mA
	B,C,E,F,G, H,J,L,M,N		310	
	DP		155	
Power Dissipation	A1,A2,D1, D2,P,K	PD	150	mW
	B,C,E,F,G, H,J,L,M,N		300	
	DP		75	
Operating Temperature		TA	-40 ~ +85	°C
Storage Temperature		Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]		260°C For 3~5 Seconds		

Operating Characteristics (TA=25°C)			UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (IF=10mA)	A1,A2,D1,D2, P,K	VF	3.6	V
	B,C,E,F,G,H, J,L,M,N		1.8	
	DP		1.8	
Forward Voltage (Max.) (IF=10mA)	A1,A2,D1,D2, P,K	VF	5.0	V
	B,C,E,F,G,H, J,L,M,N		2.5	
	DP		2.5	
Reverse Current (Max.) (VR=5V)	A1,A2,D1,D2, P,K	IR	10	uA
Reverse Current (Max.) (VR=5V)	B,C,E,F,G,H, J,L,M,N		20	
Reverse Current (Max.) (VR=5V)	DP		10	
Wavelength of Peak Emission (Typ.) (IF=10mA)		λP	660	nm
Wavelength of Dominant Emission (Typ.) (IF=10mA)		λD	640	nm
Spectral Line Full Width At Half- Maximum (Typ.) (IF=10mA)		Δλ	20	nm
Capacitance (Typ.) (VF=0V, f=1MHz)		C	45	pF

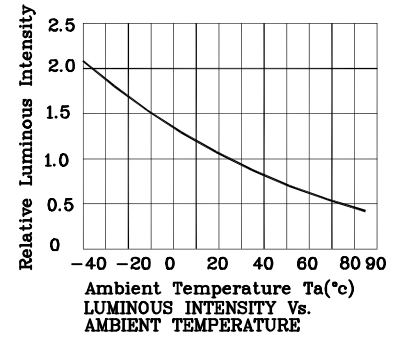
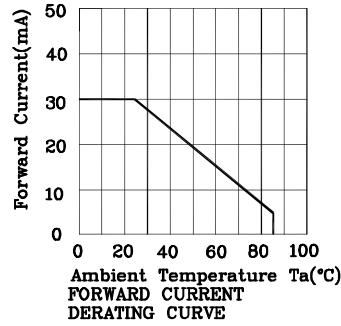
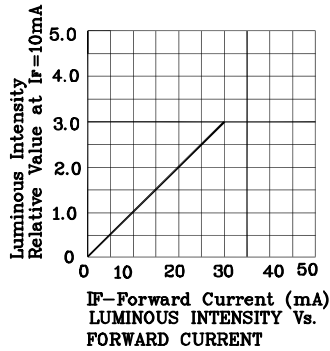
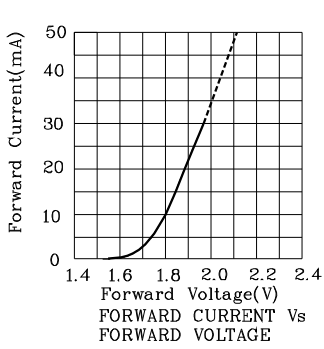
❖ MR



Note:the curves are on the segment a1,a2,d1,d2,p,k.

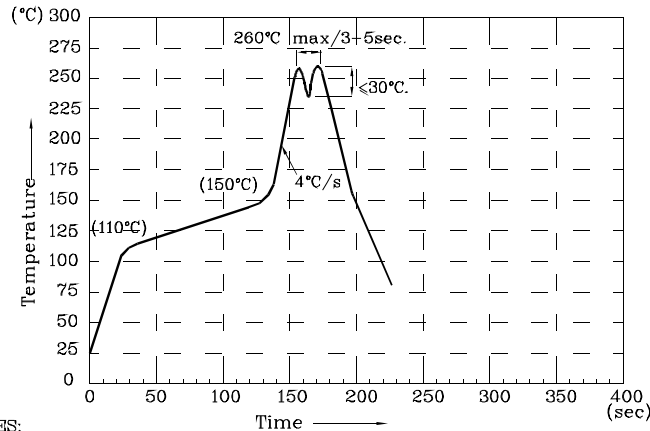


Note:the curves are on the segment b,c,e,f,g,h,j,l,m,n.



Note: the curves are on the DP.

### Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.

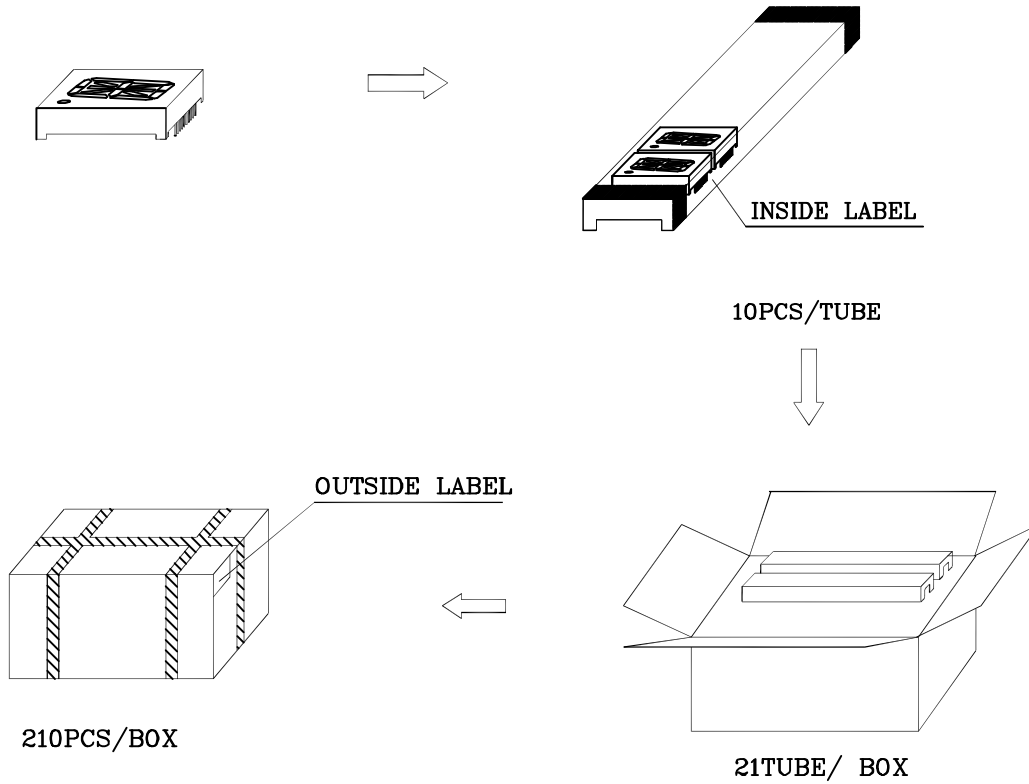
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

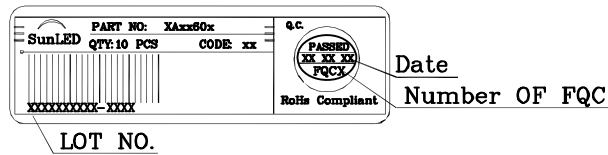
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box

